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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	ARM7®
Core Size	32-Bit Single-Core
Speed	66MHz
Connectivity	I²C, HDLC, SmartCard, SPI, UART/USART
Peripherals	PWM, WDT
Number of I/O	32
Program Memory Size	64KB (64K x 8 + 16K)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 4x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/str715fr0t6

2 Description

ARM® core with embedded Flash and RAM

The STR71x series is a family of ARM-powered 32-bit microcontrollers with embedded Flash and RAM. It combines the high performance ARM7TDMI CPU with an extensive range of peripheral functions and enhanced I/O capabilities. STR71xF devices have on-chip high-speed single voltage FLASH memory and high-speed RAM. STR710R devices have high-speed RAM but no internal Flash. The STR71x family has an embedded ARM core and is therefore compatible with all ARM tools and software.

Extensive tools support

STMicroelectronics' 32-bit, ARM core-based microcontrollers are supported by a complete range of high-end and low-cost development tools to meet the needs of application developers. This extensive line of hardware/software tools includes starter kits and complete development packages all tailored for ST's ARM core-based MCUs. The range of development packages includes third-party solutions that come complete with a graphical development environment and an in-circuit emulator/programmer featuring a JTAG application interface. These support a range of embedded operating systems (OS), while several royalty-free OSs are also available.

For more information, please refer to ST MCU site <http://www.st.com/mcu>

Table 3. STR710 BGA ball connections

	A	B	C	D	E	F	G	H	J	K	L	M
1	P0.10	P2.0	P2.1	VSS	P2.2	P2.6	BOOT EN	P2.12	P2.13	P2.15	JTDI	N.C.
2	VSS	RDn	P0.11	V33	P2.3	P2.8	P2.9	JTMS	JTRSTn	TEST	TEST	N.C.
3	V33	P0.9	P0.12	P0.13	P2.4	N.C.	P2.10	JTCK	NU	V33	N.C.	DBG RQS
4	P0.6	P0.7	P0.8	P0.14	P2.5	N.C.	P2.11	JTDO	CK	CKOUT	VSSIO-PLL	N.C.
5	A.19	WEn.1	WEn.0	P0.5	P2.7	VSS	P2.14	N.C.	RTCX-TO	RTCXTI	N.C.	P0.15
6	P0.3	A.15	A.16	A.17	A.18	V33	V18	N.C.	N.C.	V18BK P	VSS BKP	STDBY
7	P0.2	P0.1	P0.4	VSS18	V18	A.14	D.12	D.1	D.0	nc	VSS18	RSTIN
8	A.9	A.10	A.11	A.13	P0.0	A.0	D.11	P1.12/ CANTX	N.C.	AVSS	D.3	D.2
9	VSS	V33	A.5	A.6	V33	D.15	D.10	P1.8	D.9	P1.0	N.C.	N.C.
10	A.8	N.C.	P1.15	P1.13	VSS	D.14	USBDN	P1.7	D.8	P1.5	P1.1	D.4
11	A.7	N.C.	P1.14	P1.10	A.2	D.13	USBDP	VSS	D.5	P1.4	P1.3	AVDD
12	A.12	A.4	A.3	P1.9	A.1	P1.11/ CANRX	N.C.	V33IO-PLL	P1.6	D.7	D.6	P1.2

Legend / abbreviations for Table 4:

Type: I = input, O = output, S = supply, HiZ= high impedance,

In/Output level: C = CMOS 0.3V_{DD}/0.7V_{DD}

C_T= CMOS 0.3V_{DD}/0.7V_{DD} with input trigger

T_T= TTL 0.8 V/2 V with input trigger

C/T = Programmable levels: CMOS 0.3V_{DD}/0.7V_{DD} or TTL 0.8 V / 2 V

Port and control configuration:

Input: pu/pd= software enabled internal pull-up or pull down
 pu= in reset state, the internal 100kΩ weak pull-up is enabled.
 pd = in reset state, the internal 100kΩ weak pull-down is enabled.

Output: OD = open drain (logic level)
 PP = push-pull
 T = true OD, (P-Buffer and protection diode to V_{DD} not implemented),
 5 V tolerant.

Table 4. STR710 pin description

Pin n°		Pin name	Type	Reset state ¹⁾	Input		Output		Main function (after reset)	Alternate function			
LQFP144	BGA144				Input level	interrupt	Capability	OD		Active in Stby			
1	A1	P0.10/U1.RX/ U1.TX/ SC.DATA	I/O	pd	C _T	X	4mA	T	Port 0.10	UART1: Receive Data input	UART1: Transmit data output.		
										Note: This pin may be used for Smartcard DataIn/DataOut or single wire UART (half duplex) if programmed as Alternate Function Output. The pin will be tri-stated except when UART transmission is in progress			
2	B2	\overline{RD}	O	5)				X	External Memory Interface: Active low read signal for external memory. It maps to the OE_N input of the external components.				
3	C2	P0.11/BOOT.1 /U1.TX	I/O	pd	C _T		4mA	X	Port 0.11	Select Boot Configuration input	UART1: Transmit data output.		
4	C3	P0.12/SC.CLK	I/O	pd	C _T		4mA	X	Port 0.12	Smartcard reference clock output			
5	D1	V _{SS}	S						Ground voltage for digital I/Os ⁴⁾				
6	D2	V ₃₃	S						Supply voltage for digital I/Os ⁴⁾				
7	B1	P2.0/ $\overline{CS}.0$	I/O	8)	C _T		8mA	X	Port 2.0	External Memory Interface: Select Memory Bank 0 output			
										Note: This pin is forced to output push-pull 1 mode at reset to allow boot from external memory			
8	C1	P2.1/ $\overline{CS}.1$	I/O	$pu_2)$	C _T		8mA	X	Port 2.1	External Memory Interface: Select Memory Bank 1 output			
9	D3	P0.13/U2.RX/ T2.OCMPA	I/O	pu	C _T	X	4mA	X	Port 0.13	UART2: Receive Data input	Timer2: Output Compare A output		
10	D4	P0.14/U2.TX/ T2.ICAPA	I/O	pu	C _T		4mA	X	Port 0.14	UART2: Transmit data output	Timer2: Input Capture A input		
11	E1	P2.2/ $\overline{CS}.2$	I/O	$pu_2)$	C _T		8mA	X	Port 2.2	External Memory Interface: Select Memory Bank 2 output			
12	E2	P2.3/ $\overline{CS}.3$	I/O	$pu_2)$	C _T		8mA	X	Port 2.3	External Memory Interface: Select Memory Bank 3 output			

Table 5. STR711/STR712/STR715 pin description

Pin n°	Pin name	Type	Reset state ¹⁾	Input		Output		Main function (after reset)	Alternate function	
				Input level	interrupt	Capability	OD			
1	P0.10/U1.RX/ U1.TX/ SC.DATA	I/O	pd	C _T	X	4mA	T	Port 0.10	UART1: Receive Data input	UART1: Transmit data output.
									Note: This pin may be used for Smartcard DataIn/DataOut or single wire UART (half duplex) if programmed as Alternate Function Output. The pin will be tri-stated except when UART transmission is in progress	
2	P0.11/BOOT.1 /U1.TX	I/O	pd	C _T		4mA	X	Port 0.11	Select Boot Configuration input	UART1: Transmit data output.
3	P0.12/SC.CLK	I/O	pd	C _T		4mA	X	Port 0.12	Smartcard reference clock output	
4	V _{SS}	S							Ground voltage for digital I/Os ²⁾	
5	P0.13/U2.RX/ T2.OCMPA	I/O	pu	C _T	X	4mA	X	Port 0.13	UART2: Receive Data input	Timer2: Output Compare A output
6	P0.14/U2.TX/ T2.ICAPA	I/O	pu	C _T		4mA	X	Port 0.14	UART2: Transmit data output	Timer2: Input Capture A input
7	BOOTEN	I		C _T					Boot control input. Enables sampling of BOOT[1:0] pins	
8	V _{SS}	S							Ground voltage for digital I/Os ²⁾	
9	V ₃₃	S							Supply voltage for digital I/Os ²⁾	
10	JTDI	I		T _T					JTAG Data input. External pull-up required.	
11	JTMS	I		T _T					JTAG Mode Selection Input. External pull-up required.	
12	JTCK	I		C					JTAG Clock Input. External pull-up or pull-down required.	
13	JTDO	O			8mA		X		JTAG Data output. Note: Reset state = HiZ.	
14	JTRST	I		T _T					JTAG Reset Input. External pull-up required.	
15	NU								Reserved, must be forced to ground.	
16	TEST								Reserved, must be forced to ground.	
17	V _{33IO-PLL}	S							Supply voltage for digital I/O circuitry and for PLL reference ²⁾	
18	V _{SSIO-PLL}	S							Ground voltage for digital I/O circuitry and for PLL reference ²⁾	
19	CK	I		C					Reference clock input	

Table 5. STR711/STR712/STR715 pin description (continued)

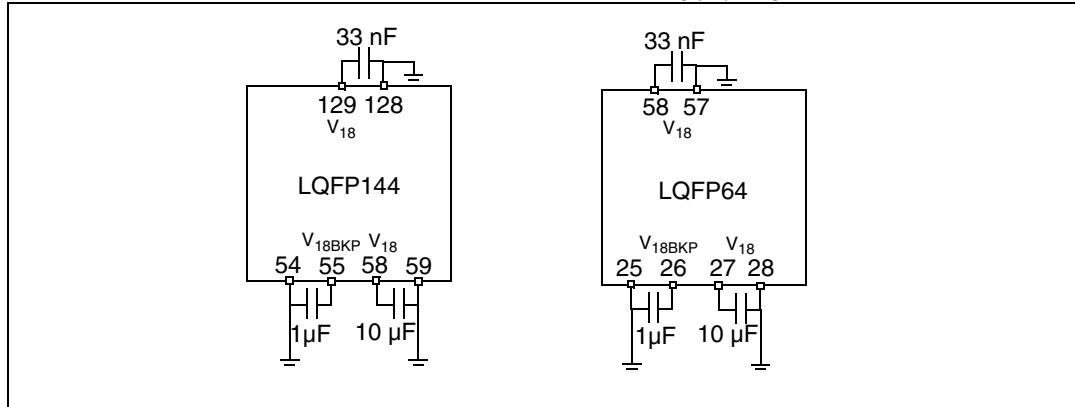
Pin n°	Pin name	Type	Reset state ¹⁾	Input		Output		Active in Stdby	Main function (after reset)	Alternate function	
				Input level	interrupt	Capability	OD				
36	P1.5/T1.ICAP B	I/O	pu	C _T		4mA	X	X		Port 1.5	Timer 1: Input Capture B
37	P1.6/T1.OCM PB	I/O	pu	C _T		4mA	X	X		Port 1.6	Timer 1: Output Compare B
38	V _{33IO-PLL}	S								Supply voltage for digital I/O circuitry and for PLL reference ²⁾	
39	V _{SSIO-PLL}	S								Ground voltage for digital I/O circuitry and for PLL reference ²⁾	
40	P1.7/T1.OCM PA	I/O	pu	C _T		4mA	X	X		Port 1.7	Timer 1: Output Compare A
41	P1.8	I/O	pd	C _T		4mA	X	X		Port 1.8	
42	P1.11/CANRX	I/O	pu	C _T	X	4mA	X	X	Port 1.11	CAN: receive data input Note: On STR710 and STR712 only	
43	P1.12/CANTX	I/O	pu	C _T		4mA	X	X	Port 1.12	CAN: Transmit data output Note: On STR710 and STR712 only	
42	USBDP	I/O		C _T						USB bidirectional data (data +). Reset state = HiZ Note: On STR710 and STR711 only This pin requires an external pull-up to V ₃₃ to maintain a high level.	
43	USBDN	I/O		C _T						USB bidirectional data (data -). Reset state = HiZ Note: On STR710 and STR711 only.	
44	V _{SS}	S								Ground voltage for digital I/O circuitry ²⁾	
45	P1.9	I/O	pd	C _T		4mA	X	X	Port 1.9		
46	P1.10/USBCL K	I/O	pd	C/ T		4mA	X	X	Port 1.10	USB: 48 MHZ clock input	
47	P1.13/HCLK/I 0.SCL	I/O	pd	C _T	X	4mA	X	X	Port 1.13	HDLC: reference clock input	I2C clock
48	P1.14/HRXD/I 0.SDA	I/O	pu	C _T	X	4mA	X	X	Port 1.14	HDLC: Receive data input	I2C serial data
49	P1.15/HTXD	I/O	pu	C _T		4mA	X	X	Port 1.15	HDLC: Transmit data output	
50	V _{SS}	S								Ground voltage for digital I/O circuitry ²⁾	
51	V ₃₃	S								Supply voltage for digital I/O circuitry ²⁾	

Table 5. STR711/STR712/STR715 pin description (continued)

Pin n°	Pin name	Type	Reset state ¹⁾	Input		Output		Active in Stdby	Main function (after reset)	Alternate function	
				Input level	interrupt	Capability	OD				
63	P0.8/U0.RX/U0.TX	I/O	pd	C _T	X	4mA	T		Port 0.8	UART0: Receive Data input	UART0: Transmit data output.
										Note: This pin may be used for single wire UART (half duplex) if programmed as Alternate Function Output. The pin will be tri-stated except when UART transmission is in progress	
64	P0.9/U0.TX/BOOT.0	I/O	pd	C _T		4mA	X	X	Port 0.9	Select Boot Configuration input	UART0: Transmit data output

1. The Reset configuration of the I/O Ports is IPUPD (input pull-up/pull down). Refer to [Table 6 on page 30](#). The Port bit configuration at reset is PC0=1, PC1=1, PC2=0. The port data register bit (PD) value depends on the pu/pd column which specifies whether the pull-up or pull-down is enabled at reset
2. V_{33IO-PLL} and V₃₃ are internally connected. V_{SSIO-PLL} and V_{SS} are internally connected.

3.5 External connections

Figure 5. Recommended external connection of V₁₈ and V_{18BKP} pins

3.7 Memory mapping

Figure 6. Memory map

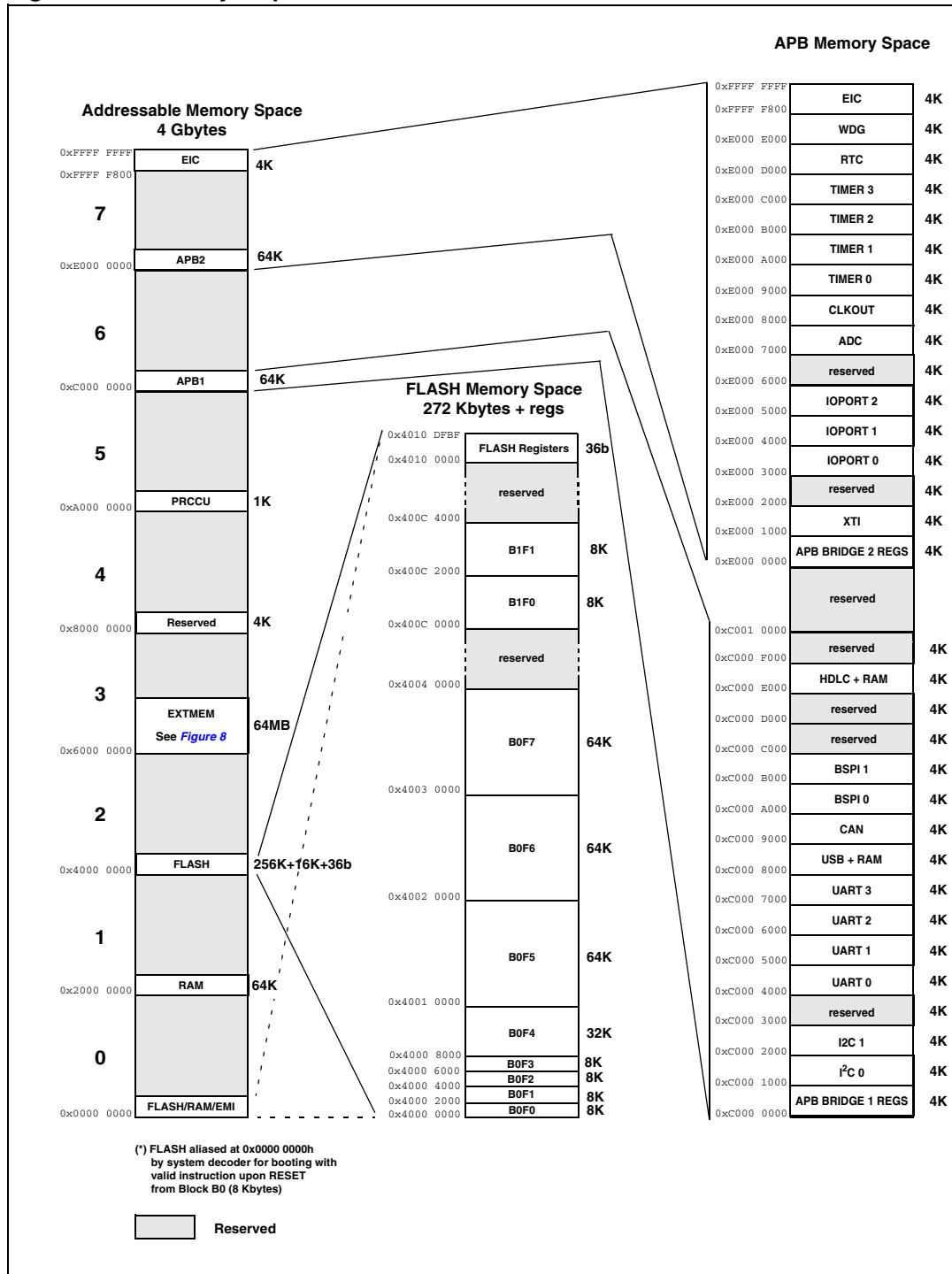


Figure 8. External memory map

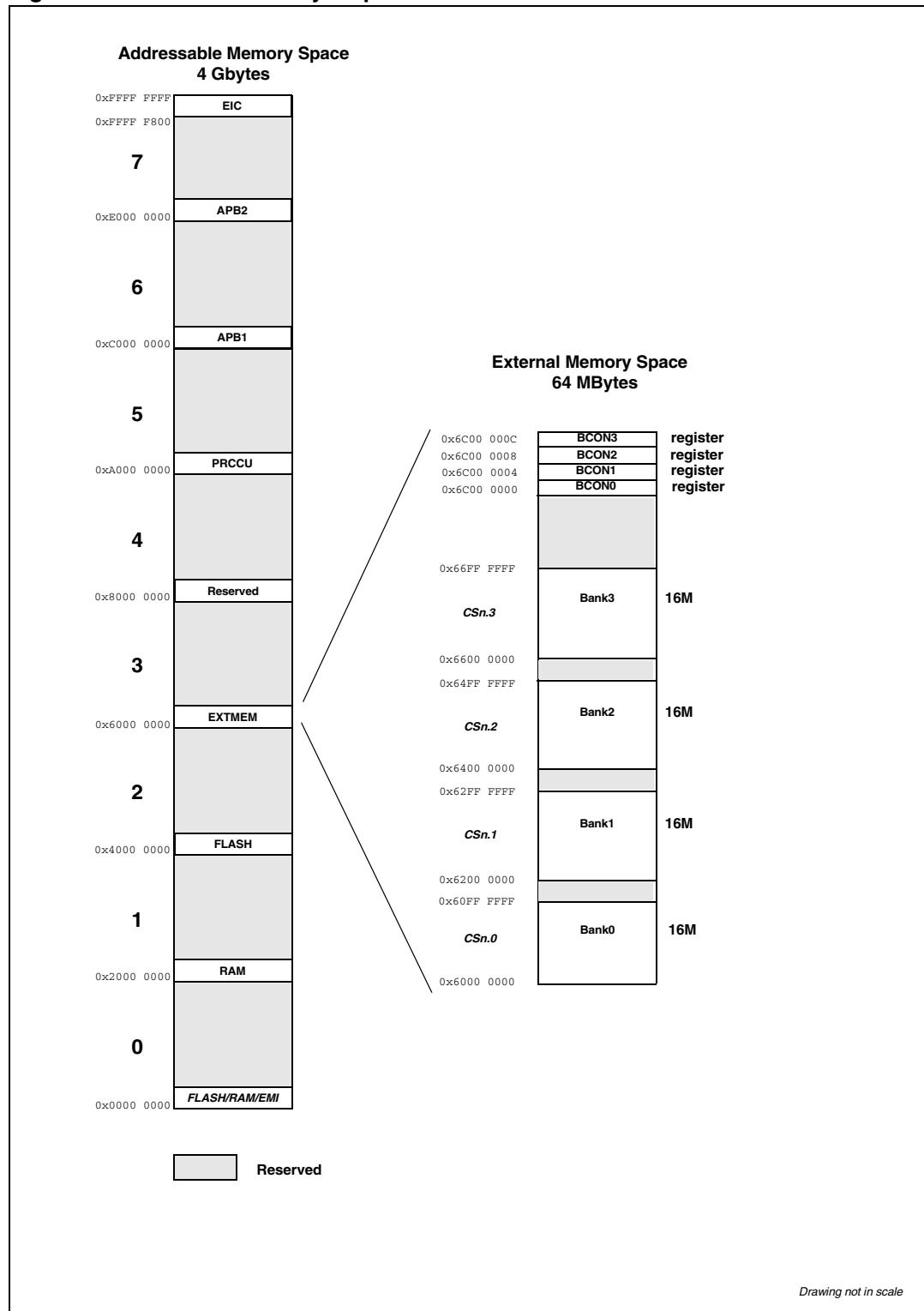


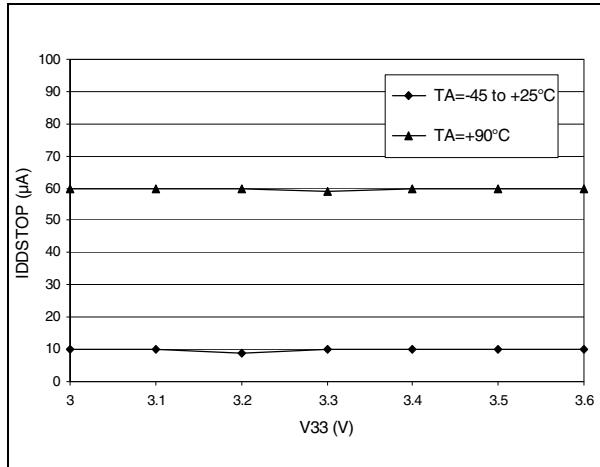
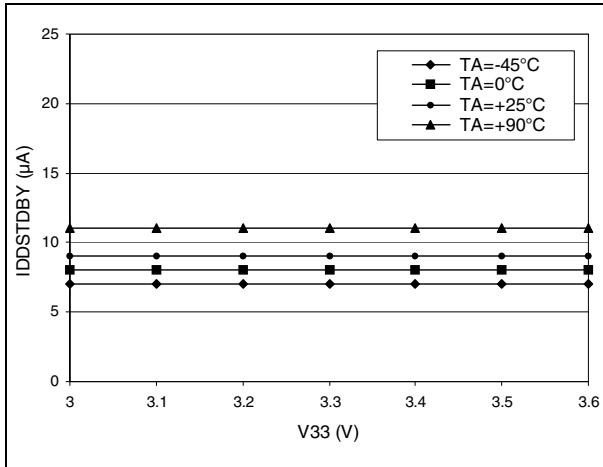
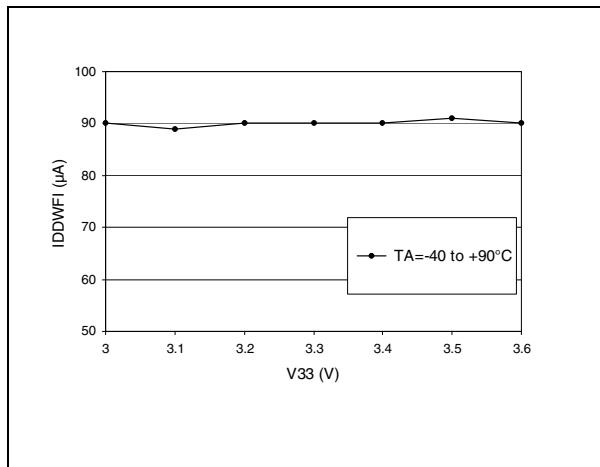
Figure 11. STOP I_{DD} vs. V₃₃**Figure 12. STANDBY I_{DD} vs. V₃₃****Figure 13. WFI I_{DD} vs. V₃₃**

Table 19. PLL1 characteristics (continued)

Symbol	Parameter	Test conditions	Value			Unit
			Min	Typ	Max	
$\Delta t_{JITTER1}$	PLL jitter (peak to peak)	$t_{PLL} = 4 \text{ MHz}$, $MX[1:0] = '11'$ Global Output division = 32 (Output Clock = 2 MHz)		0.7	2	ns

Table 20. PLL2 characteristics

Symbol	Parameter	Test conditions	Value			Unit
			Min	Typ	Max	
$f_{PLLCLK2}$	PLL multiplier output clock				140	MHz
f_{PLL2}	PLL input clock	FREF_RANGE = 0	1.5		3.0	MHz
		FREF_RANGE = 1	3.0		5	MHz
t_{LOCK2}	PLL lock time	FREF_RANGE = 0 Stable Input Clock Stable $V_{33IOPLL}, V_{18}$			300	μs
		FREF_RANGE = 1 Stable Input Clock Stable $V_{33IOPLL}, V_{18}$			600	μs
$\Delta t_{JITTER2}$	PLL jitter (peak to peak)	$t_{PLL} = 4 \text{ MHz}, MX[1:0] = '11'$ Global Output division = 32 (Output Clock = 2 MHz)		0.7	2	ns

Table 21. Low-power mode wakeup timing

Symbol	Parameter	Typ	Unit
$t_{WULPWFI}$	Wakeup from LPWFI mode	26 ⁽¹⁾	μs
t_{WUSTOP}	Wakeup from STOP mode	2048	CLK Cycles ⁽²⁾
t_{WUSTBY}	Wakeup from STANDBY mode	2048 CLK Cycles + 8 CLK2 Cycles ⁽³⁾	Cycles

1. Clock selected is CK2_16, Main VReg OFF and Flash in power-down
2. The CLK clock is derived from the external oscillator.
3. Refer to Figure 7. Reset General Timing in the STR71xF Reference Manual (UM0084)

4.3.5 I/O port pin characteristics

General characteristics

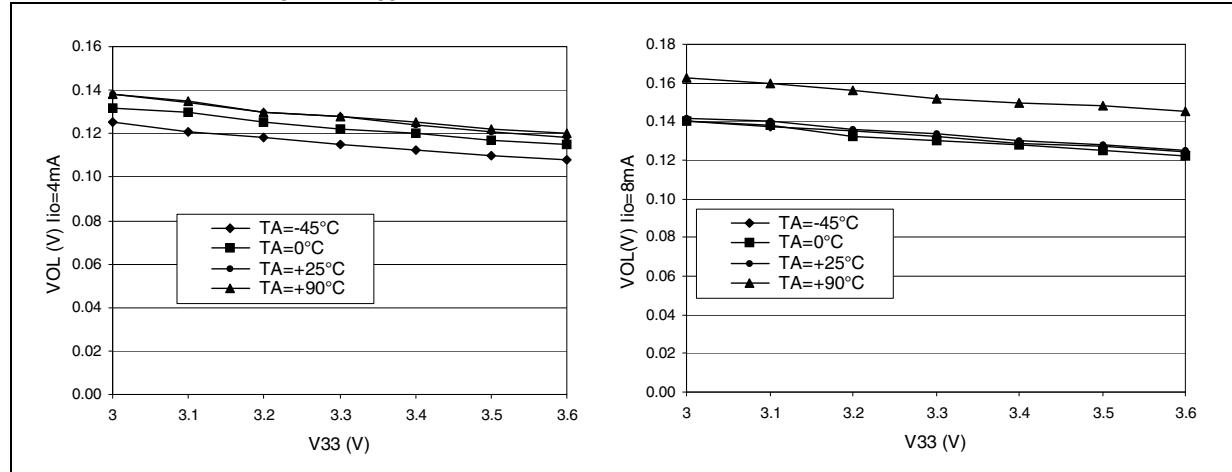
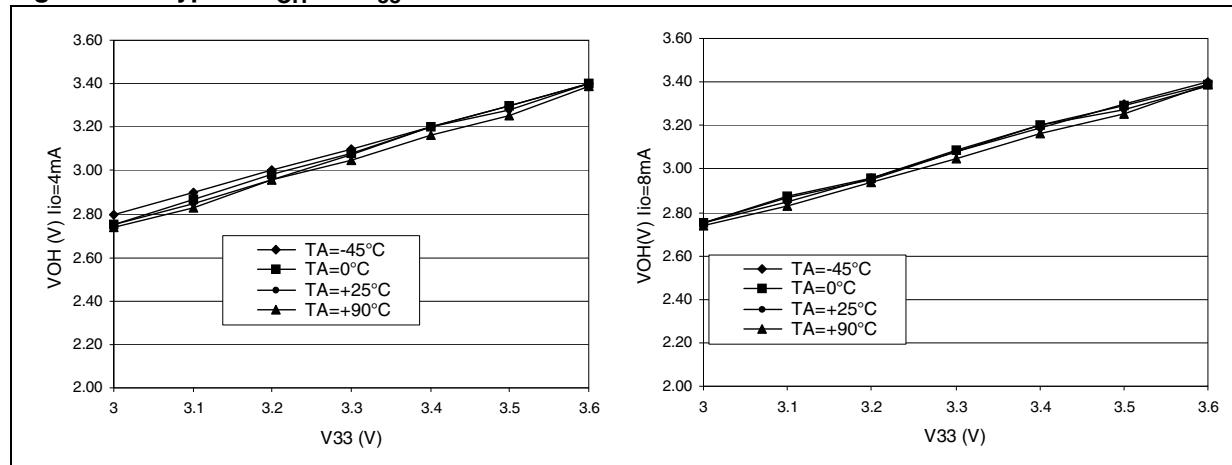
Subject to general operating conditions for V_{33} and T_A unless otherwise specified. All unused pins must be kept at a fixed voltage: using the output mode of the I/O for example or an external pull-up or pull-down resistor.

Table 27. I/O static characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IL}	Input low level voltage ¹⁾	CMOS ports			$0.3V_{33}$	V
V_{IH}	Input high level voltage ¹⁾		$0.7V_{33}$			
V_{hys}	Schmitt trigger voltage hysteresis ²⁾			0.8		V
V_{IL}	Input low level voltage ¹⁾	P0.15 WAKEUP		0.9	0.8	V
V_{IH}	Input high level voltage ¹⁾		2	1.35		
V_{hys}	Schmitt trigger voltage hysteresis ²⁾			0.4		V
V_{IL}	Input low level voltage ¹⁾	TTL ports			0.8	V
V_{IH}	Input high level voltage ¹⁾		2.0			
$I_{INJ(PIN)}$	Injected Current on any I/O pin				± 4	mA
$\Sigma I_{INJ(PIN)}$ ³⁾	Total injected current (sum of all I/O and control pins)				± 25	
I_{Ikg}	Input leakage current ⁴⁾	$V_{SS} \leq V_{IN} \leq V_{33}$			± 1	μA
R_{PU}	Weak pull-up equivalent resistor ⁵⁾	$V_{IN}=V_{SS}$	110	150	700	$k\Omega$
R_{PD}	Weak pull-down equivalent resistor ⁵⁾	$V_{IN}=V_{33}$	110	150	700	$k\Omega$
C_{IO}	I/O pin capacitance			5		pF

Notes:

1. Data based on characterization results, not tested in production.
2. Hysteresis voltage between Schmitt trigger switching levels. Based on characterization results, not tested.
3. When the current limitation is not possible, the V_{IN} absolute maximum rating must be respected, otherwise refer to $I_{INJ(PIN)}$ specification. A positive injection is induced by $V_{IN}>V_{33}$ while a negative injection is induced by $V_{IN}<V_{SS}$. Refer to [Section 4.2 on page 35](#) for more details.
4. Leakage could be higher than max. if negative current is injected on adjacent pins.
5. The R_{PU} pull-up and R_{PD} pull-down equivalent resistor are based on a resistive transistor (corresponding I_{PU} and I_{PD} current characteristics described in [Figure 18](#) to [Figure 19](#)).

Figure 22. Typical V_{OL} vs. V_{33} **Figure 23. Typical V_{OH} vs. V_{33}** 

RSTIN pin

The **RSTIN** pin input driver is CMOS. A permanent pull-up is present which is the same as R_{PU} (see [Table 27 on page 51](#))

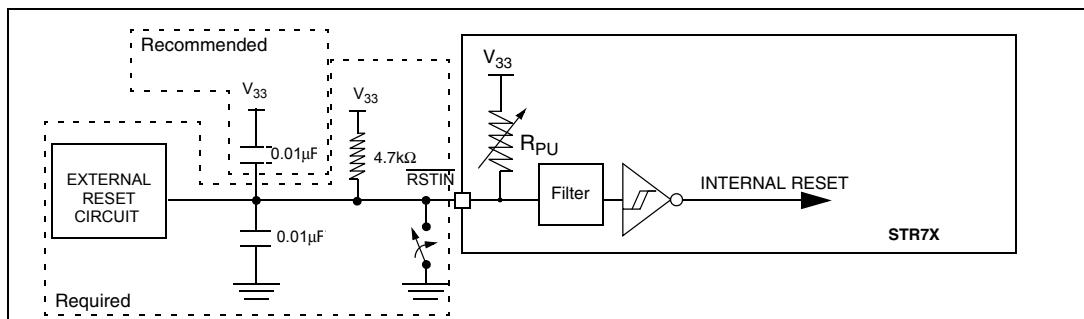
Subject to general operating conditions for V_{33} and T_A unless otherwise specified.

Table 29. RESET pin characteristics

Symbol	Parameter	Conditions	Min	Typ ¹⁾	Max	Unit
$V_{IL(RSTINn)}$	RSTIN Input low level voltage ¹⁾			0.8		V
$V_{IH(RSTINn)}$	RSTIN Input high level voltage ¹⁾		2			
$V_{F(RSTINn)}$	RSTIN Input filtered pulse ²⁾			500		ns
$V_{NF(RSTINn)}$	RSTIN Input not filtered pulse ²⁾		1.2			μs

Notes:

1. Data based on characterization results, not tested in production.
- 2) Data guaranteed by design, not tested in production.

Figure 24. Recommended RSTIN pin protection.¹⁾**Notes:**

1. The R_{PU} pull-up equivalent resistor is based on a resistive transistor (corresponding I_{PU} current characteristics described in [Figure 18](#)).
2. The reset network protects the device against parasitic resets.
3. The user must ensure that the level on the RSTIN pin can go below the $V_{IL(RSTINn)}$ max. level specified in [Table 29](#). Otherwise the reset will not be taken into account internally.

4.3.9 BSPI - buffered serial peripheral interface

Subject to general operating conditions for V_{DD} , T_A and f_{PCLK1} , unless otherwise specified.

Refer to [I/O port pin characteristics on page 51](#) for more details on the input/output alternate function characteristics (\overline{SS} , SCK, MOSI, MISO).

Table 36. BSPI characteristics

Symbol	Parameter	Conditions	Min	Max	Unit
f_{SCK} $1/t_c(SCK)$	SPI clock frequency	Master	$f_{PCLK1}/254$	$f_{PCLK1}/6$ 5.5	MHz
		Slave	0	$f_{PCLK1}/8$ 3.3	
$t_r(SCK)$ $t_f(SCK)$	SPI clock rise and fall time	capacitive charge $C=50\text{ pF}$		14	ns
$t_{su}(\overline{SS})^{(1)}$	\overline{SS} setup time	Slave	0		
$t_h(\overline{SS})^{(1)}$	\overline{SS} hold time	Slave	0		
$t_w(SCKH)^{(1)}$ $t_w(SCKL)^{(1)}$	SCK high and low time	Master $f_{PCLK1}=33\text{ MHz}$, presc = 6	73		
$t_{su(MI)}^{(1)}$ $t_{su(SI)}^{(1)}$	Data input setup time	Master Slave	7 0		
$t_h(MI)^{(1)(2)}$ $t_h(SI)^{(1)(2)}$	Data input hold time	Master Slave	$1xt_{PCLK1}$ $2xt_{PCLK1}$		
$t_h(MI)^{(1)}$ $t_h(SI)^{(1)}$	Data input hold time	Master $f_{PCLK1}=33\text{ MHz}$ Slave $f_{PCLK1}=33\text{ MHz}$	30 60		
$t_a(SO)^{(1)(3)}$	Data output access time	Slave	0	$1.5xt_{PCLK1}+42$	
		Slave $f_{PCLK1}=33\text{ MHz}$	0	87	
$t_{dis(SO)}^{(1)(4)}$	Data output disable time	Slave	0	42	
$t_v(SO)^{(1)(2)}$	Data output valid time	Slave (after enable edge)		$3xt_{PCLK1}+45$	
		$f_{PCLK1}=33\text{ MHz}$		135	
$t_h(SO)^{(1)}$	Data output hold time	Slave (after enable edge)	0		
$t_v(MO)^{(1)(2)}$	Data output valid time	Master (after enable edge)		$2xt_{PCLK1}+12$	
		$f_{PCLK1}=33\text{ MHz}$		72	
$t_h(MO)^{(1)}$	Data output hold time	Master (after enable edge)	0		

1. Data based on design simulation and/or characterisation results, not tested in production.
2. Depends on f_{PCLK1} . For example, if $f_{PCLK1}=8\text{ MHz}$, then $t_{PCLK1} = 1/f_{PCLK1} = 125\text{ ns}$ and $t_{v(MO)} = 255\text{ ns}$.
3. Min. time is the minimum time to drive the output and the max. time is the maximum time to validate the data.
4. Min time is the minimum time to invalidate the output and the max time is the maximum time to put the data in Hi-Z.

5 Package characteristics

5.1 Package mechanical data

Figure 40. 64-Pin low profile quad flat package (10x10)

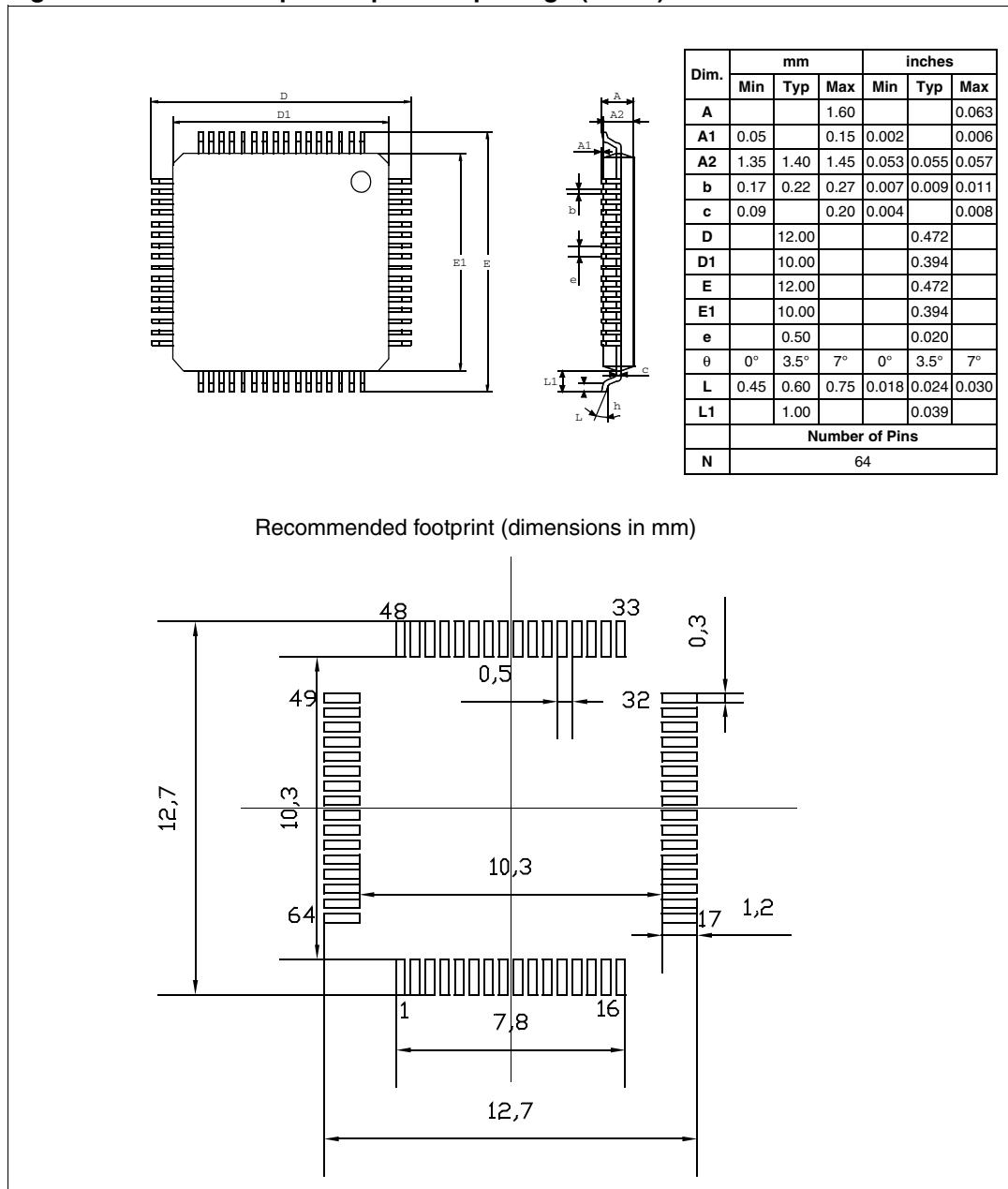
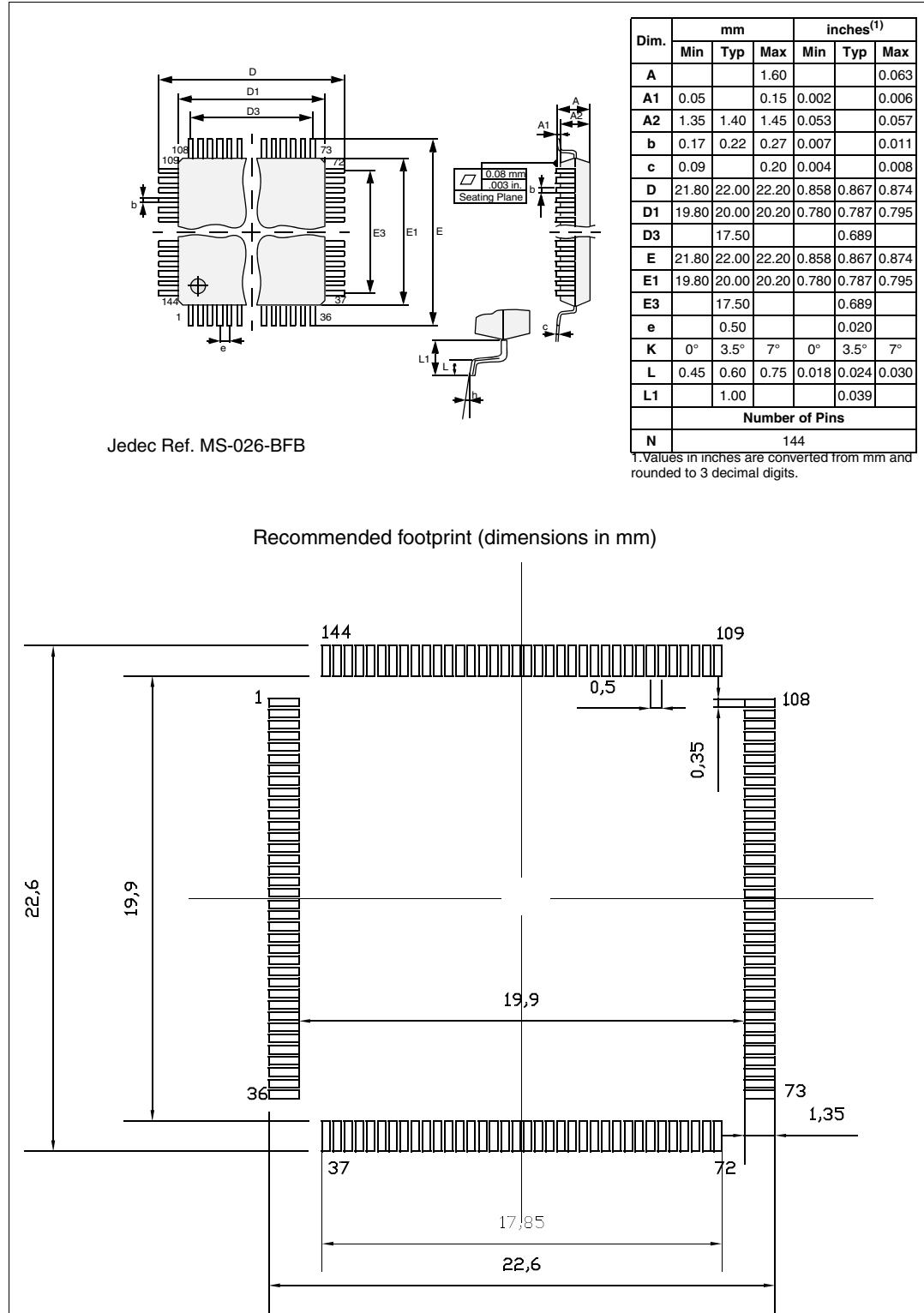


Figure 41. 144-Pin low profile quad flat package



6 Product history

There are three versions of the STR710F series products. All versions are functionally identical and differ only with the points listed below.

Version "A" was the first version produced and delivered. Version "Z" was the second in production replacing version "A". Version "Z" has lower power consumption in STOP mode.

Version "X" is the latest introduced.

Marking

The difference between versions is visible on the marking of the product as shown in the four examples in [Figure 45](#) through [Figure 48](#).

Figure 45. LQFP144 STR710 version "A"

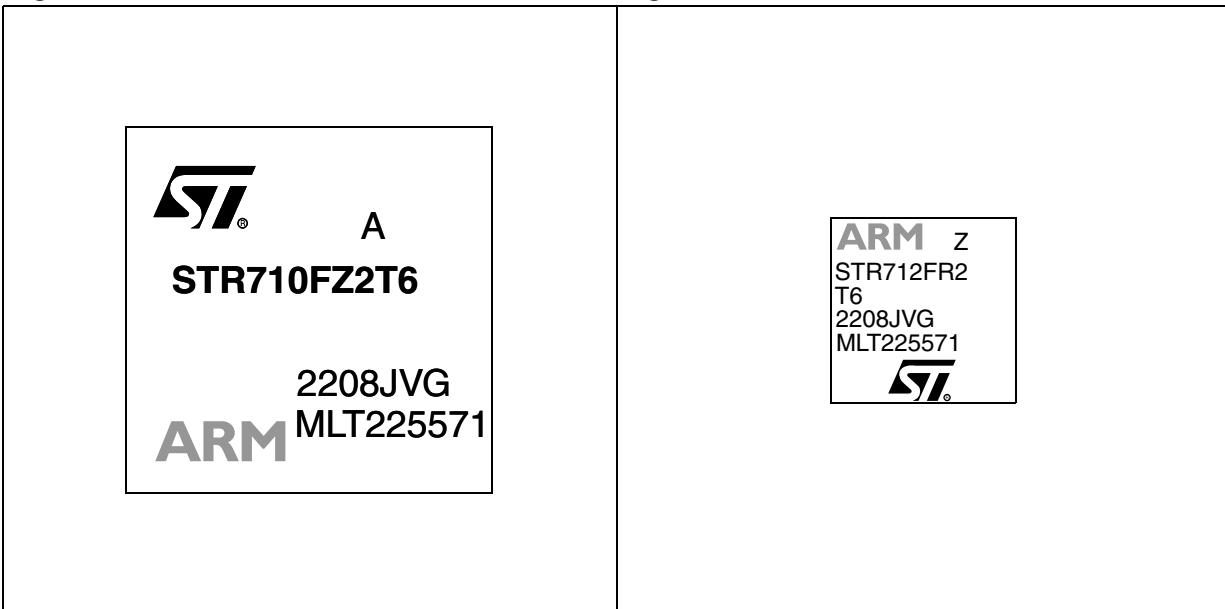
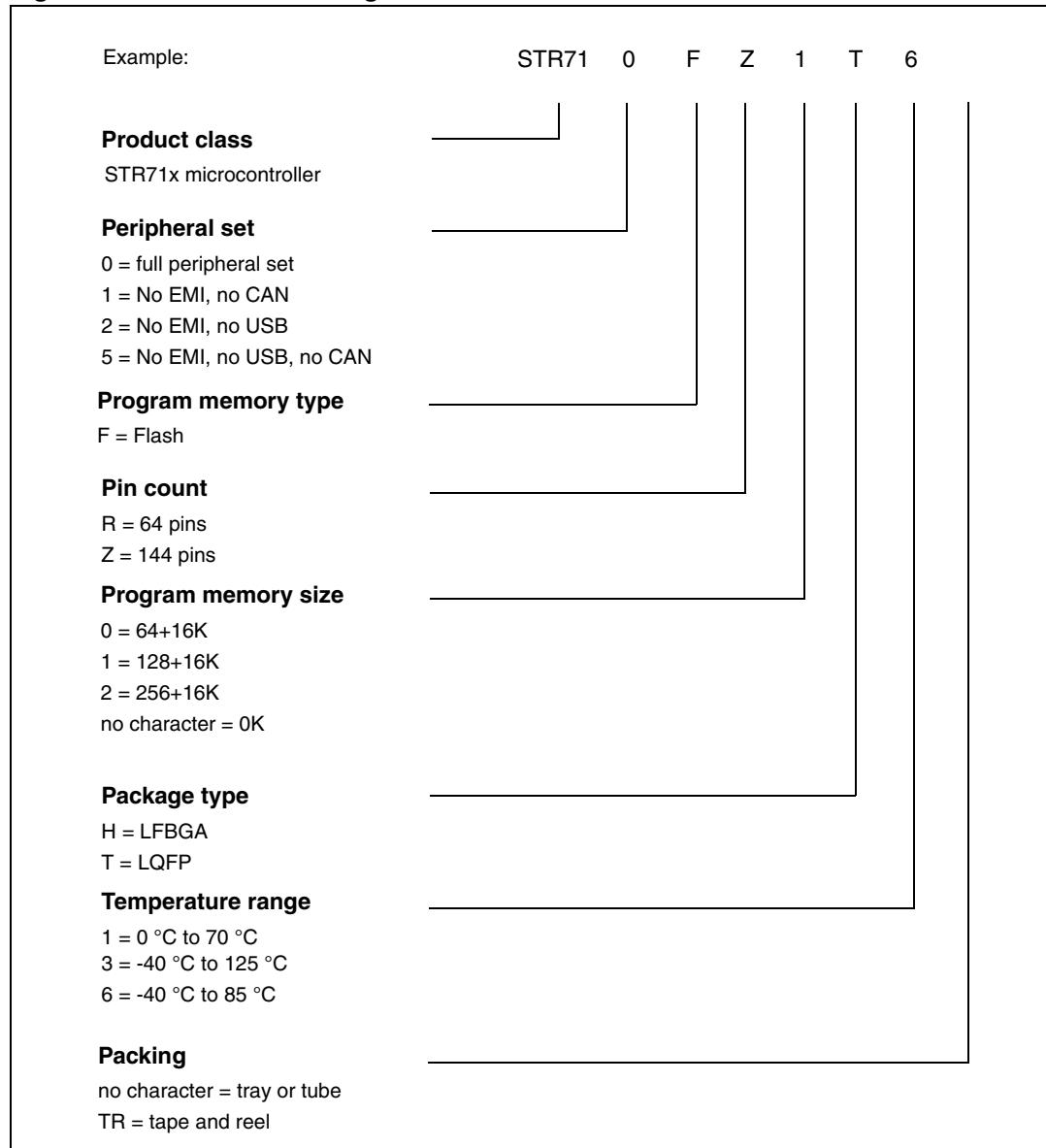


Figure 46. LQFP64 STR712 version "Z"



7 Ordering information

Figure 49. STR71xF ordering information scheme



1. For a list of available options (e.g. memory size, package) and orderable part numbers or for further information on any aspect of this device, please go to www.st.com or contact the ST Sales Office nearest to you.

8 Known limitations

Description

If an IRQ or FIQ interrupt is pending and the Interrupt vector register (EIC_IVR) is not yet read, the HALT bit in the RCCU_SMR register can not be written. Therefore a software reset can not be generated.

Workaround

To generate a software reset when an IRQ or FIQ line is pending, either:

- reset the EIC peripheral by setting bit 14 in the APB2_SWRES register, or
- read the EIC_IVR register prior to generating a software reset.

9 Revision history

Table 44. Document revision history

Date	Revision	Changes
17-Mar-2004	1	First Release
05-Apr-2004	2	Updated "Electrical parameters" on page 34
08-Apr-2004	2.1	Corrected STR712F Pinout. Pins 43/42 swapped.
15-Apr-2004	2.2	PDF hyperlinks corrected.
7-Jul-2004	3	Corrected description of STDBY, V18, VSS18 V18BKP VSSBKP pins Added IDDrun typical data Updated BSPI max. baudrate. Updated "EMI - external memory interface" on page 56
29-Oct-2004	4	Corrected Flash sector B1F0/F1 address in Figure 6: Memory map on page 31 Corrected Table 5 on page 25 LQFP64 TEST pin is 16 instead of 17. Added to TQPFP64 column: pin 7 BOOTEN, pin 17 V _{33IO} -PLL Changed description of JTCK from 'External pull-down required' to 'External pull-up or pull down required'.
25-Jan-2005	5	Changed "Product Preview" to "Preliminary Data" on page 1 and 3 Renamed 'PU/PD' column to 'Reset state' in Table 5 on page 25 Added reference to STR7 Flash Programming Reference Manual
19-Apr-2005	6	Added STR715F devices and modified RAM size of STR71xF1 devices Added BGA package in Section 5 Updated ordering information in Section 7 . Added PLL duty cycle min and max. in PLL electrical characteristics on page 45
13-Oct-2005	7	Updated feature description on page 1 Update overview Section 1.1 Added OD/PP to P0.12 in Table 5 Changed name of WFI mode to WAIT mode Changed Memory Map Table 6 : Ext. Memory changed to 64 MB and flash register changed to 36 bytes. Added Power Consumption Table 13 Modified BGA144 F3, F5, F12 and G12 in Table 3 and Table 4 Update EMI Timing Table 24 and Figure 29